

BRCS1C0P06MF

Rev.B Aug.-2024

/ Descriptions

SOT23-6 P

P- CHANNEL MOSFET in a SOT23 -6 Plastic Package.

/

$V_{DS}=-60V$; $I_D=-3A$

$R_{DS(on)1}@-10V$ 100m (Type.83m)

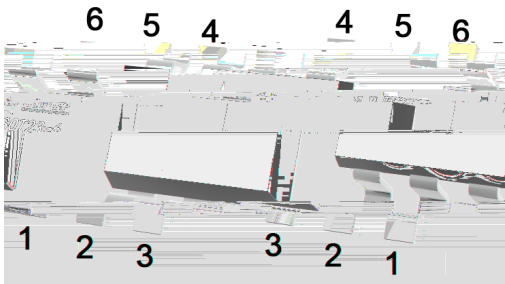
$R_{DS(on)2}@-4.5V$ 130m (Type.100m)

HF Product.

PWM

PWM application & Load switch.

/ Equivalent Circuit



PIN1 D PIN 2 D PIN 3 G PIN 4 S PIN 5 D PIN 6 D

/ Marking

See Marking Instructions.

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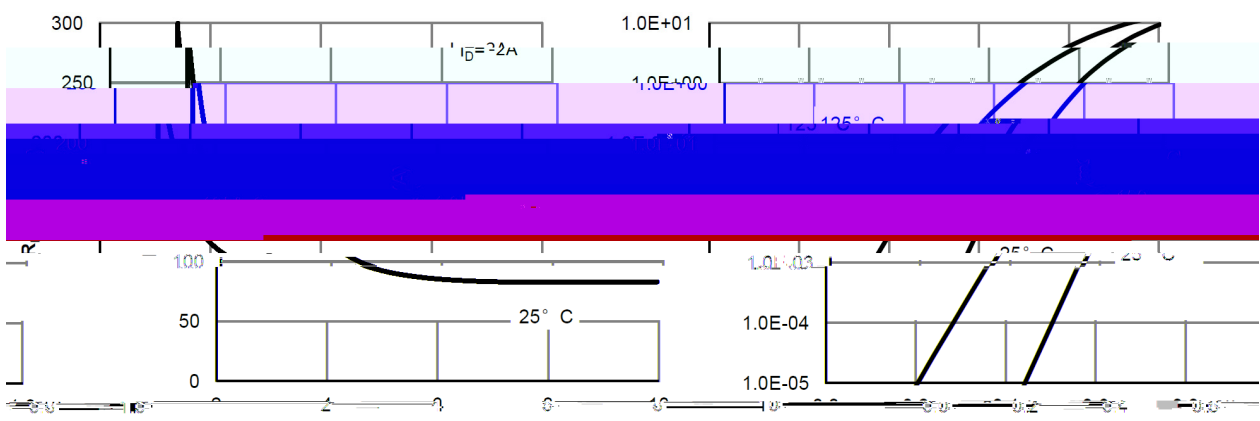
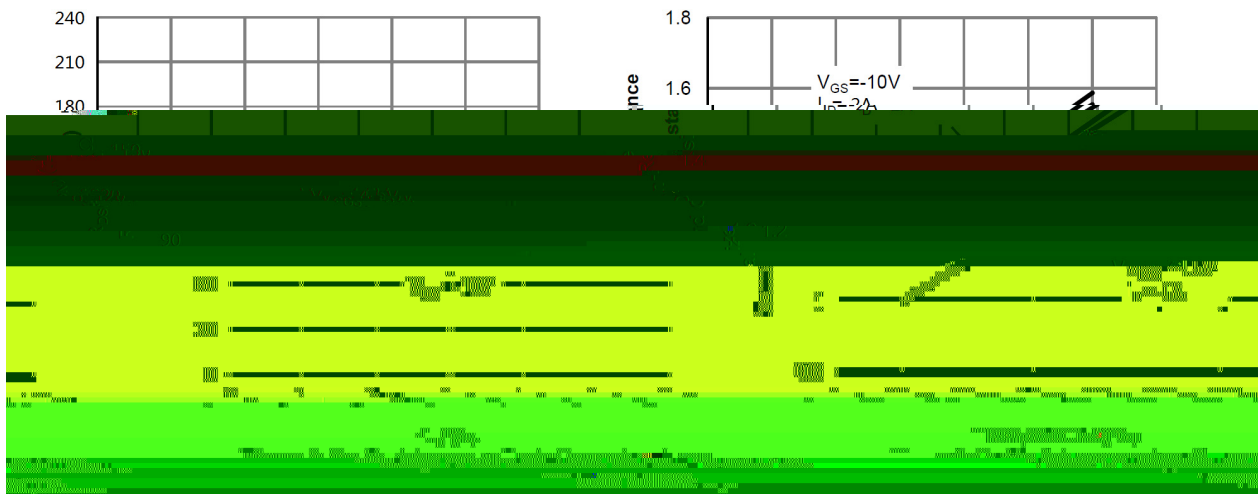
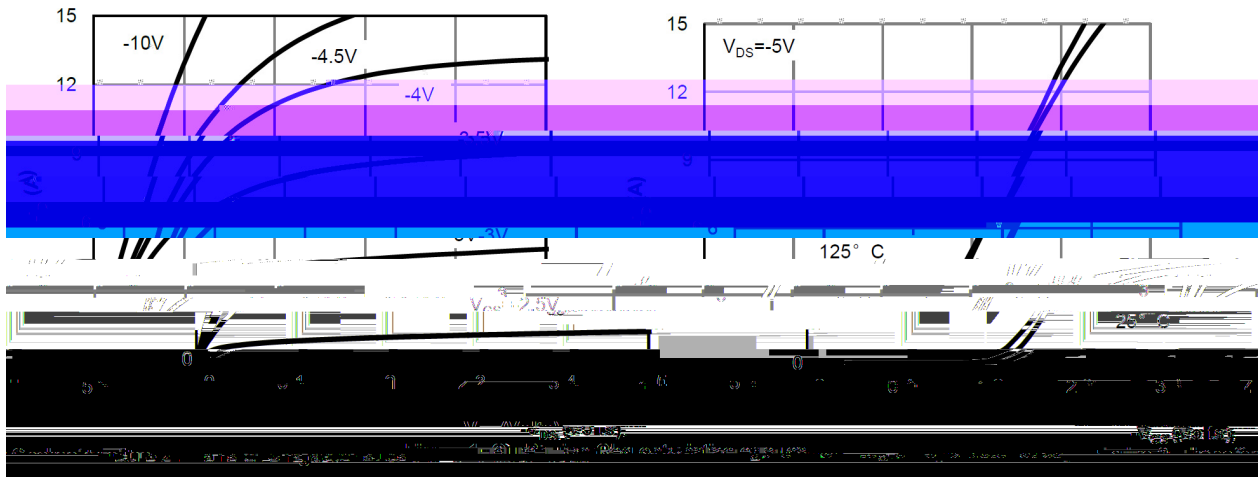
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DATA SHEET

Parameter	Symbol	Rating	Unit
Drain–Source Voltage	V_{DSS}	-60	V
Gate–Body Leakage Voltage	V_{GSS}	± 20	V
Drain Current – Continuous	I_D	-3	A
Pulsed Drain Current	I_{DM}	-16	A
Power Dissipation	P_D	1.4	W

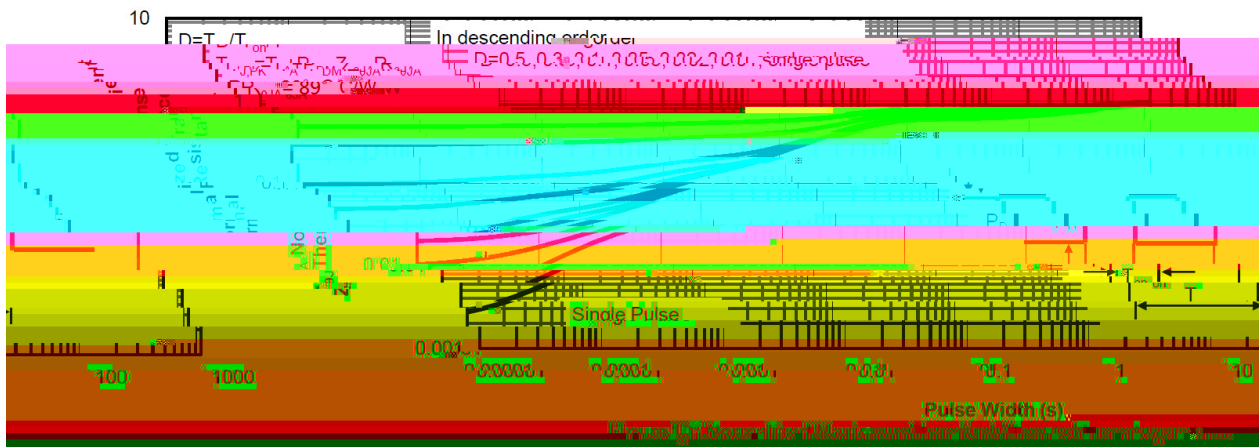
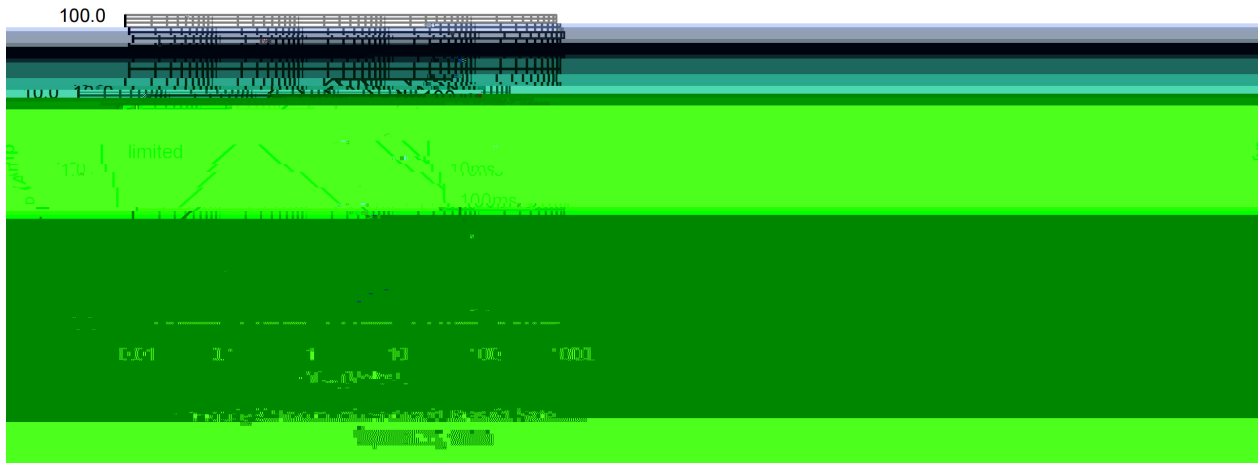
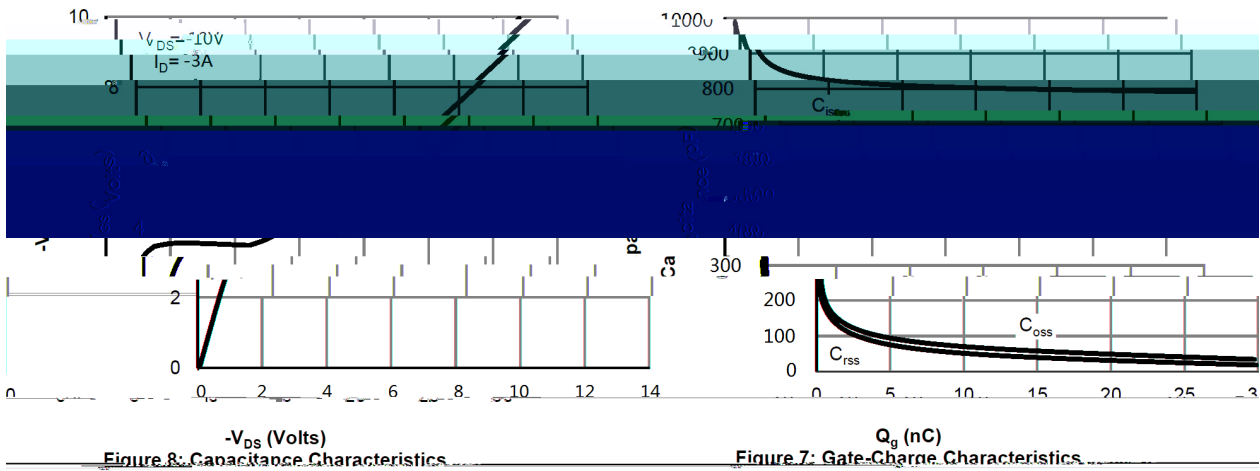
/ Electrical Characteristic Curve



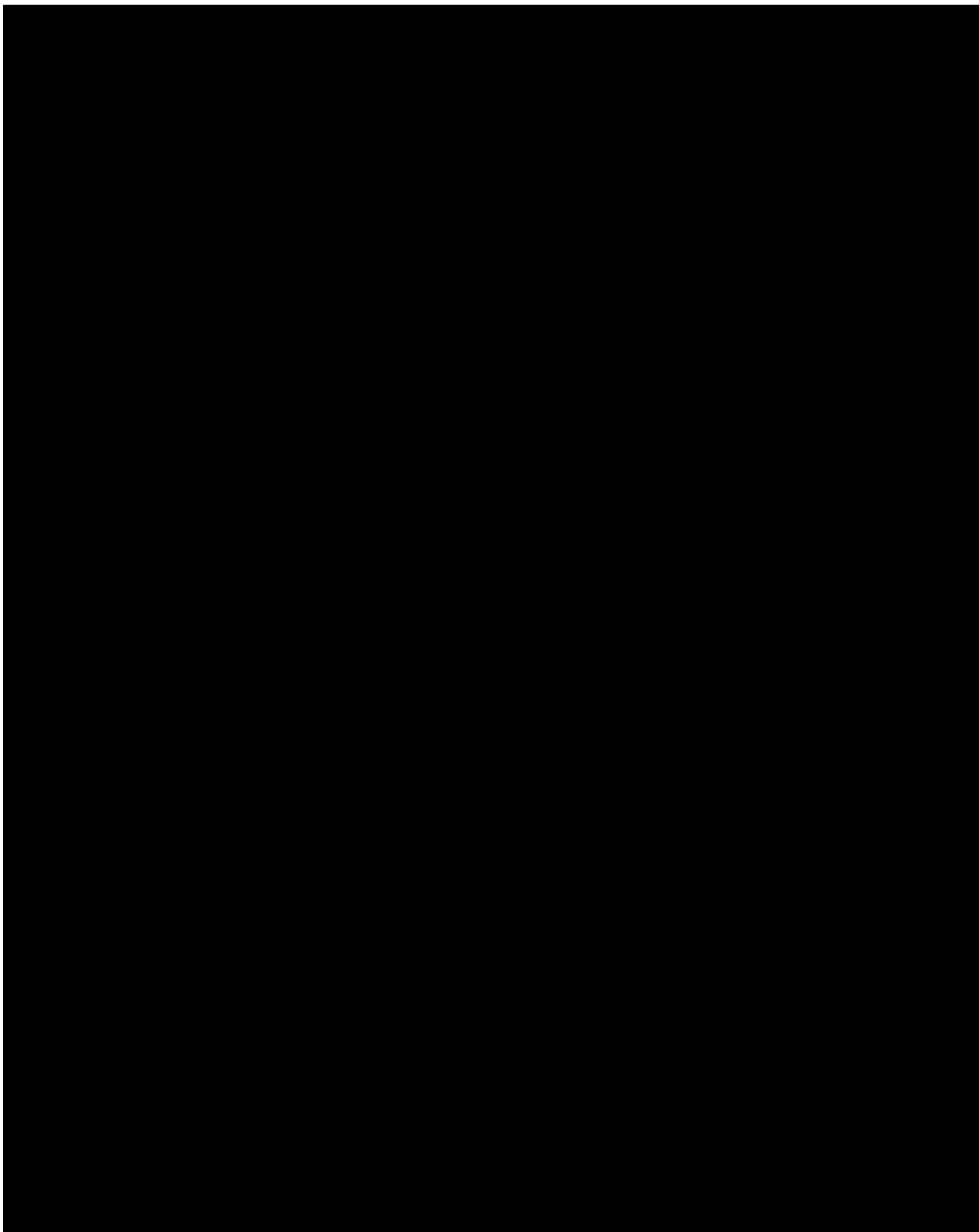
eristics **Figure 5: On-Resistance vs. Gate-Source Voltage**

Figure 6: Body-Diode Character

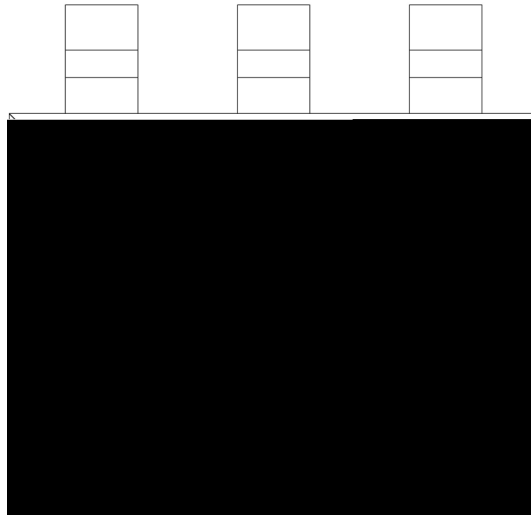
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



C1:
H
****.

Note:

- C1: Product Type Code
- H: Company Code
- **** Lot No. Code, code change with Lot No.

() / Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

- | | | | |
|---|-----------|-------------|---|
| 1 | 150 ~ 180 | 60 ~ 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | 2 ~ 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec
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/ Packaging SPEC.

/ REEL

Package Type	Units	Dimension	(unit mm ³)
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